


[Click here for the 3D model.](#)
General Information

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|--------------------------|--------------------------------------------|
| Series | KONNEKT KC-LINK Comm COG |
| Style | KONNEKT |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss |
| RoHS | Yes |
| Termination | Tin |
| Typical Component Weight | 600 mg |
| Notes | 2-Chip Standard Orientation. |
| MSL | 1 |
| Case Code (EIA / mm) | 2220 / 5651 |

Dimensions

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|---|-----------------|
| L | 5.7mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| T | 5mm +/-0.4mm |
| B | 0.6mm +/-0.35mm |

Packaging Specifications

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|--------------------|------------|
| Packaging | T&R, 180mm |
| Packaging Quantity | 300 |

Specifications

| | |
|--------------------------------------------------------------------|-------------------------|
| Capacitance | 0.2 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 500 VDC |
| Dielectric Withstanding Voltage | 750 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1 kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 5 GOhms |

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